

# BT169D-L

Thyristor logic level

Rev. 02 — 26 February 2008

Product data sheet

## 1. Product profile

### 1.1 General description

Passivated sensitive gate thyristor in a SOT54 plastic package.

### 1.2 Features

- Very sensitive gate
- Direct interfacing to logic level ICs
- Direct interfacing to low power gate drive circuits

### 1.3 Applications

- General purpose switching and phase control

### 1.4 Quick reference data

- $V_{DRM} \leq 400\text{ V}$
- $V_{RRM} \leq 400\text{ V}$
- $I_{TSM} \leq 8\text{ A}$  ( $t = 10\text{ ms}$ )
- $I_{T(RMS)} \leq 0.8\text{ A}$
- $I_{T(AV)} \leq 0.5\text{ A}$
- $I_{GT} \leq 50\text{ }\mu\text{A}$

## 2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode (A)	 3 2 1 SOT54 (TO-92)	 A — — K G sym037
2	gate (G)		
3	cathode (K)		

### 3. Ordering information

**Table 2. Ordering information**

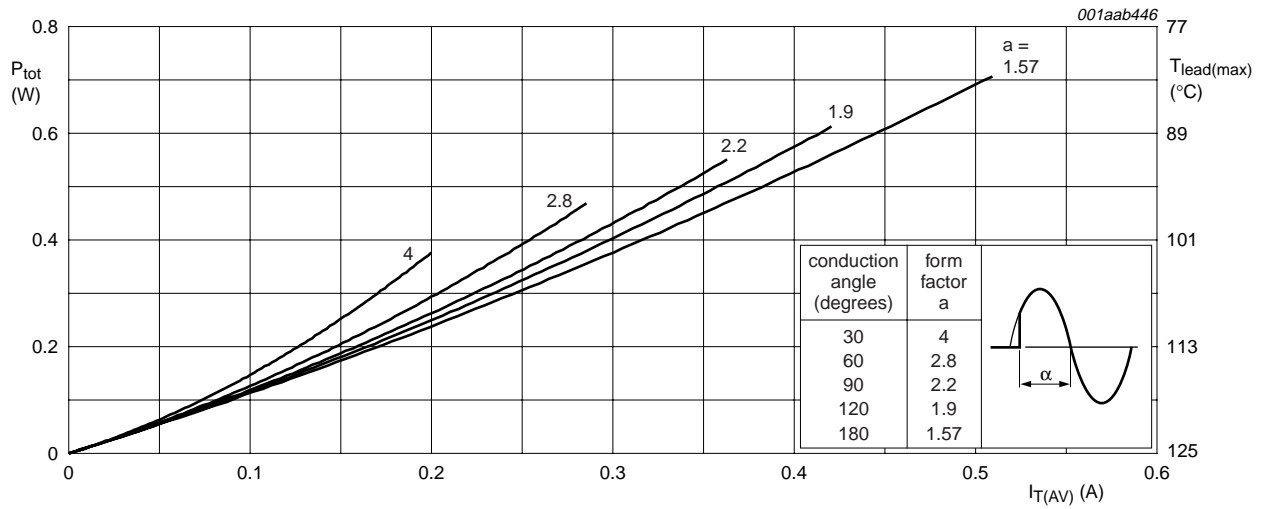
Type number	Package		Version
	Name	Description	
BT169D-L	TO-92	plastic single-ended leaded (through hole) package; 3 leads	SOT54

### 4. Limiting values

**Table 3. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	400	V
$V_{RRM}$	repetitive peak reverse voltage		-	400	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{lead} \leq 83\text{ °C}$ ; see <a href="#">Figure 1</a>	-	0.5	A
$I_{T(RMS)}$	RMS on-state current	all conduction angles; see <a href="#">Figure 4</a> and <a href="#">5</a>	-	0.8	A
$I_{TSM}$	non-repetitive peak on-state current	half sine wave; $T_j = 25\text{ °C}$ prior to surge; see <a href="#">Figure 2</a> and <a href="#">3</a>			
		$t = 10\text{ ms}$	-	8	A
		$t = 8.3\text{ ms}$	-	9	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$	-	0.32	$A^2s$
$di_T/dt$	rate of rise of on-state current	$I_{TM} = 2\text{ A}$ ; $I_G = 10\text{ mA}$ ; $di_G/dt = 100\text{ mA}/\mu s$	-	50	$A/\mu s$
$I_{GM}$	peak gate current		-	1	A
$V_{RGM}$	peak reverse gate voltage		-	5	V
$P_{GM}$	peak gate power		-	2	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.1	W
$T_{stg}$	storage temperature		-40	+150	$^{\circ}C$
$T_j$	junction temperature		-	125	$^{\circ}C$



Form factor  $a = I_{T(RMS)} / I_{T(AV)}$

Fig 1. Total power dissipation as a function of average on-state current; maximum values

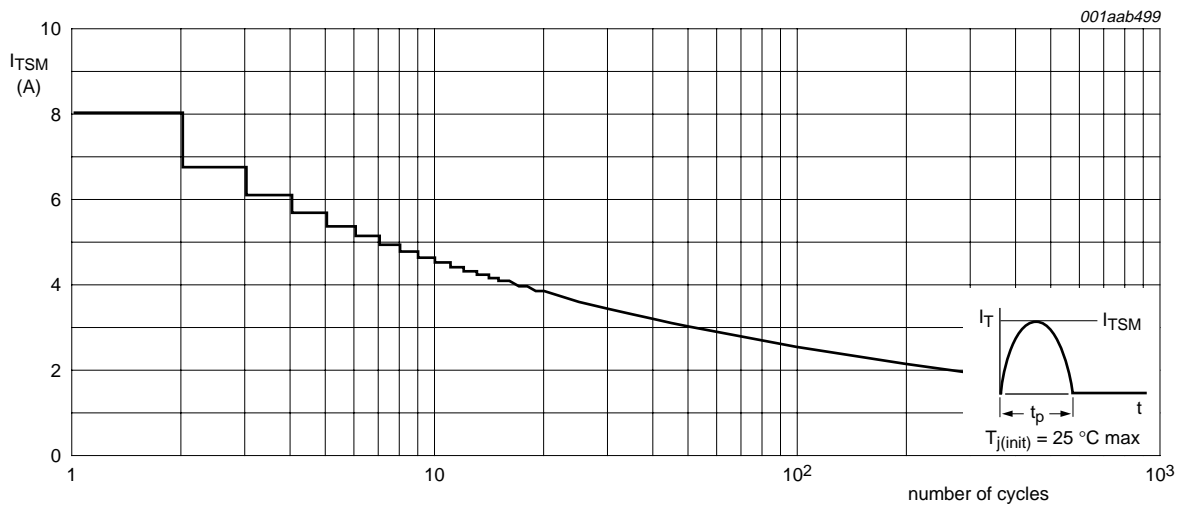
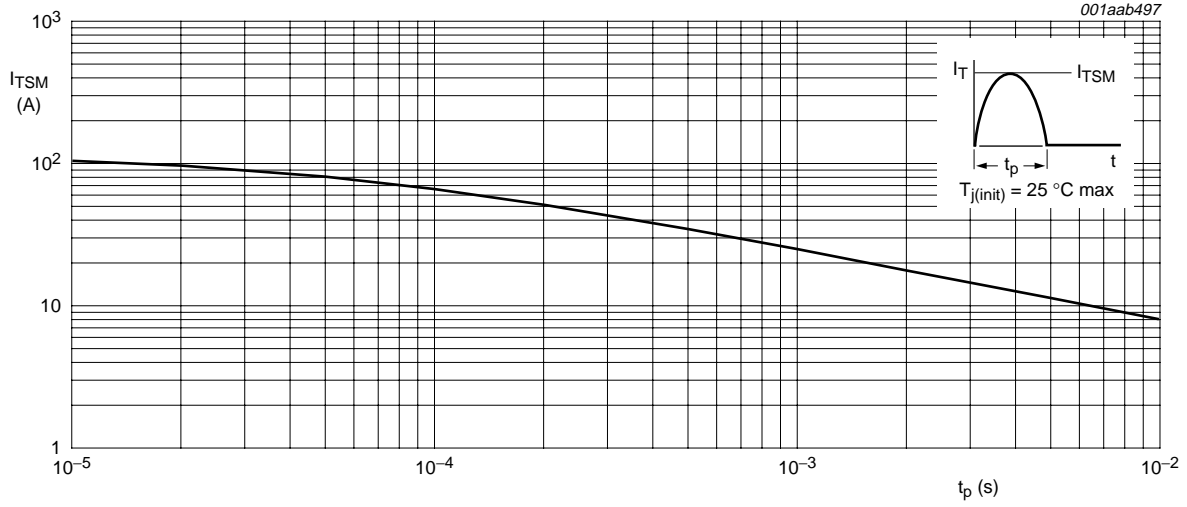
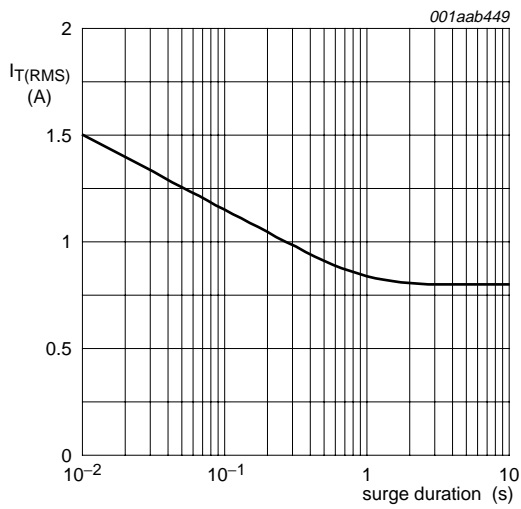


Fig 2. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



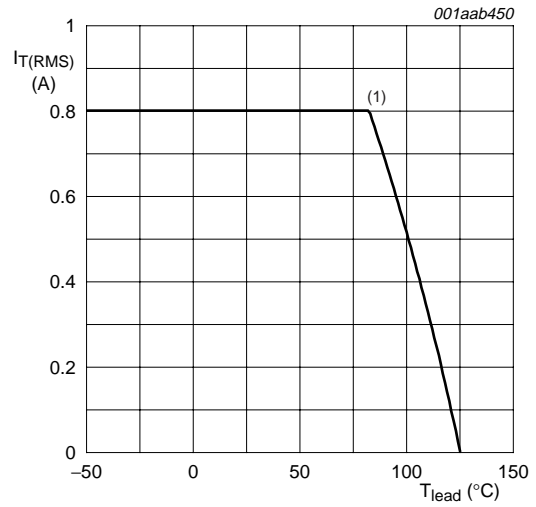
$t_p \leq 10\text{ ms}$

**Fig 3. Non-repetitive peak on-state current as a function of pulse width for sinusoidal currents; maximum values**



$f = 50\text{ Hz}; T_{lead} \leq 83\text{ °C}$

**Fig 4. RMS on-state current as a function of surge duration for sinusoidal currents**



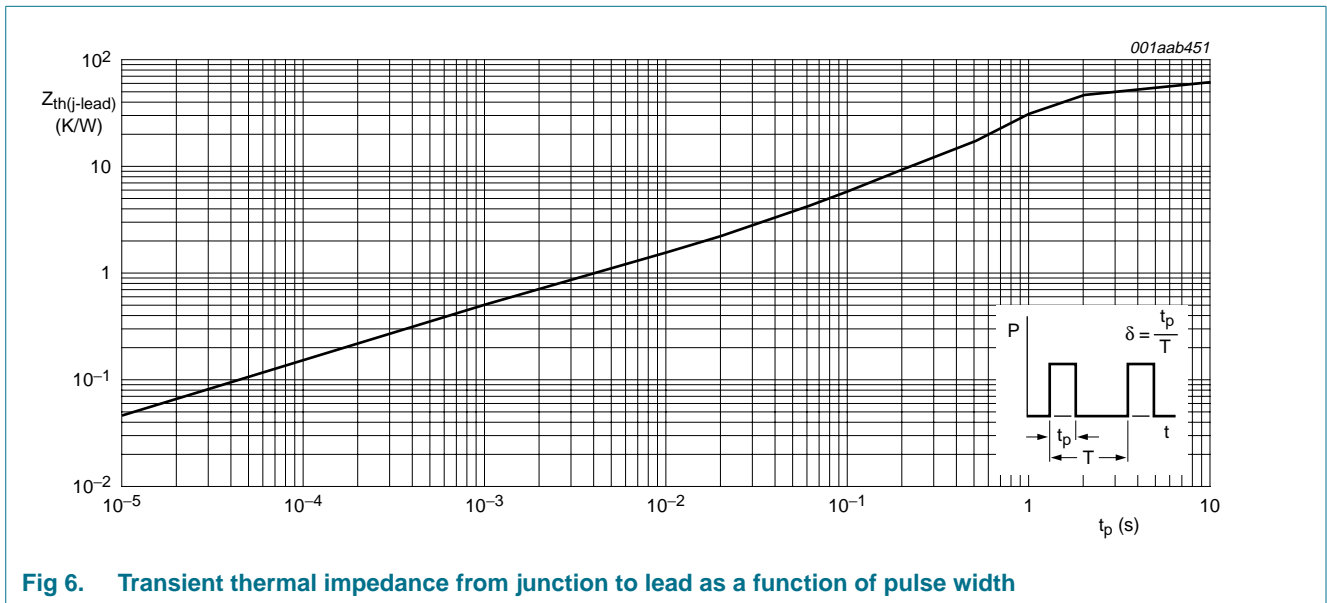
(1)  $T_{lead} = 83\text{ °C}$

**Fig 5. RMS on-state current as a function of lead temperature; maximum values**

### 5. Thermal characteristics

**Table 4. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-lead)}$	thermal resistance from junction to lead	see <a href="#">Figure 6</a>	-	-	60	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	printed-circuit board mounted; lead length = 4 mm	-	150	-	K/W



**Fig 6. Transient thermal impedance from junction to lead as a function of pulse width**

## 6. Characteristics

**Table 5. Characteristics**

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise stated.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}$ ; $I_T = 10\text{ mA}$ ; see <a href="#">Figure 8</a>	-	-	50	$\mu\text{A}$
$I_L$	latching current	$V_D = 12\text{ V}$ ; $I_G = 0.5\text{ mA}$ ; $R_{GK} = 1\text{ k}\Omega$ ; see <a href="#">Figure 10</a>	-	2	6	mA
$I_H$	holding current	$V_D = 12\text{ V}$ ; $I_G = 0.5\text{ mA}$ ; $R_{GK} = 1\text{ k}\Omega$ ; see <a href="#">Figure 11</a>	-	2	5	mA
$V_T$	on-state voltage	$I_T = 1.2\text{ A}$	-	1.25	1.7	V
$V_{GT}$	gate trigger voltage	$I_T = 10\text{ mA}$ ; see <a href="#">Figure 7</a>	-	-	-	-
		$V_D = 12\text{ V}$	-	0.5	0.8	V
		$V_D = V_{DRM(max)}$ ; $T_j = 125\text{ }^\circ\text{C}$	0.2	0.3	-	V
$I_D$	off-state current	$V_D = V_{DRM(max)}$ ; $T_j = 125\text{ }^\circ\text{C}$ ; $R_{GK} = 1\text{ k}\Omega$	-	0.05	0.1	mA
<b>Dynamic characteristics</b>						
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 0.67 \times V_{DRM(max)}$ ; $T_j = 125\text{ }^\circ\text{C}$ ; exponential waveform; see <a href="#">Figure 12</a>	-	-	-	-
		$R_{GK} = 1\text{ k}\Omega$	500	800	-	V/ $\mu\text{s}$
		gate open circuit	-	25	-	V/ $\mu\text{s}$
$t_{gt}$	gate-controlled turn-on time	$I_{TM} = 2\text{ A}$ ; $V_D = V_{DRM(max)}$ ; $I_G = 10\text{ mA}$ ; $dI_G/dt = 0.1\text{ A}/\mu\text{s}$	-	2	-	$\mu\text{s}$
$t_q$	commutated turn-off time	$V_{DM} = 0.67 \times V_{DRM(max)}$ ; $T_j = 125\text{ }^\circ\text{C}$ ; $I_{TM} = 1.6\text{ A}$ ; $V_R = 35\text{ V}$ ; $(dI_T/dt)_M = 30\text{ A}/\mu\text{s}$ ; $dV_D/dt = 2\text{ V}/\mu\text{s}$ ; $R_{GK} = 1\text{ k}\Omega$	-	100	-	$\mu\text{s}$

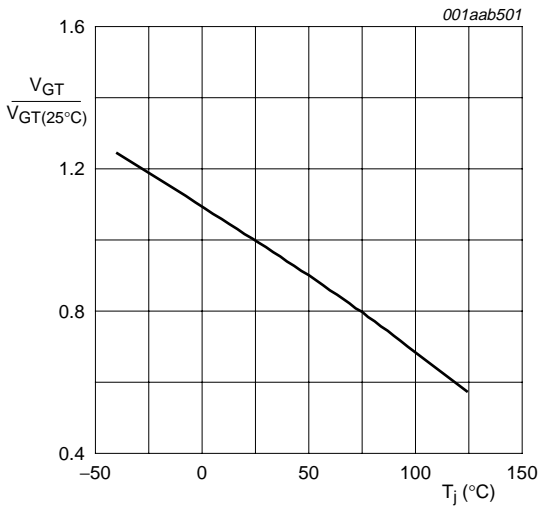


Fig 7. Normalized gate trigger voltage as a function of junction temperature

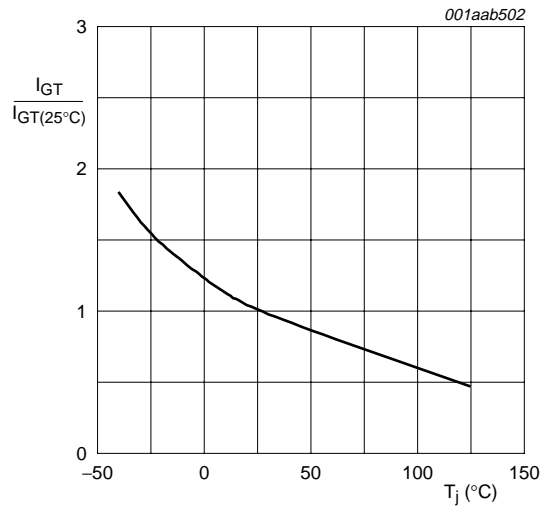
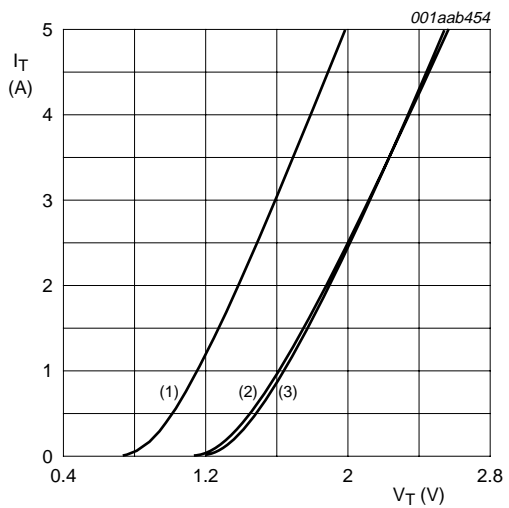
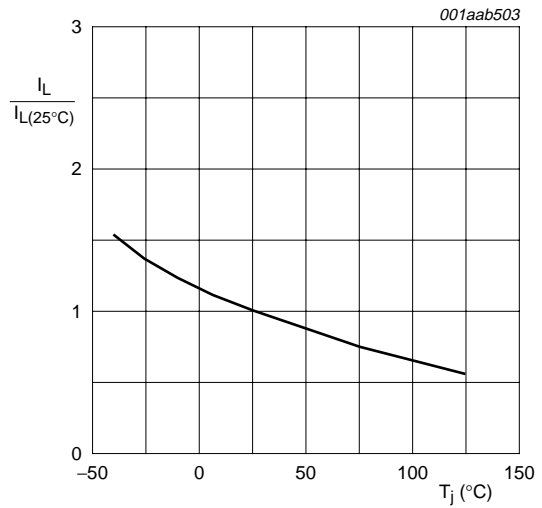


Fig 8. Normalized gate trigger current as a function of junction temperature



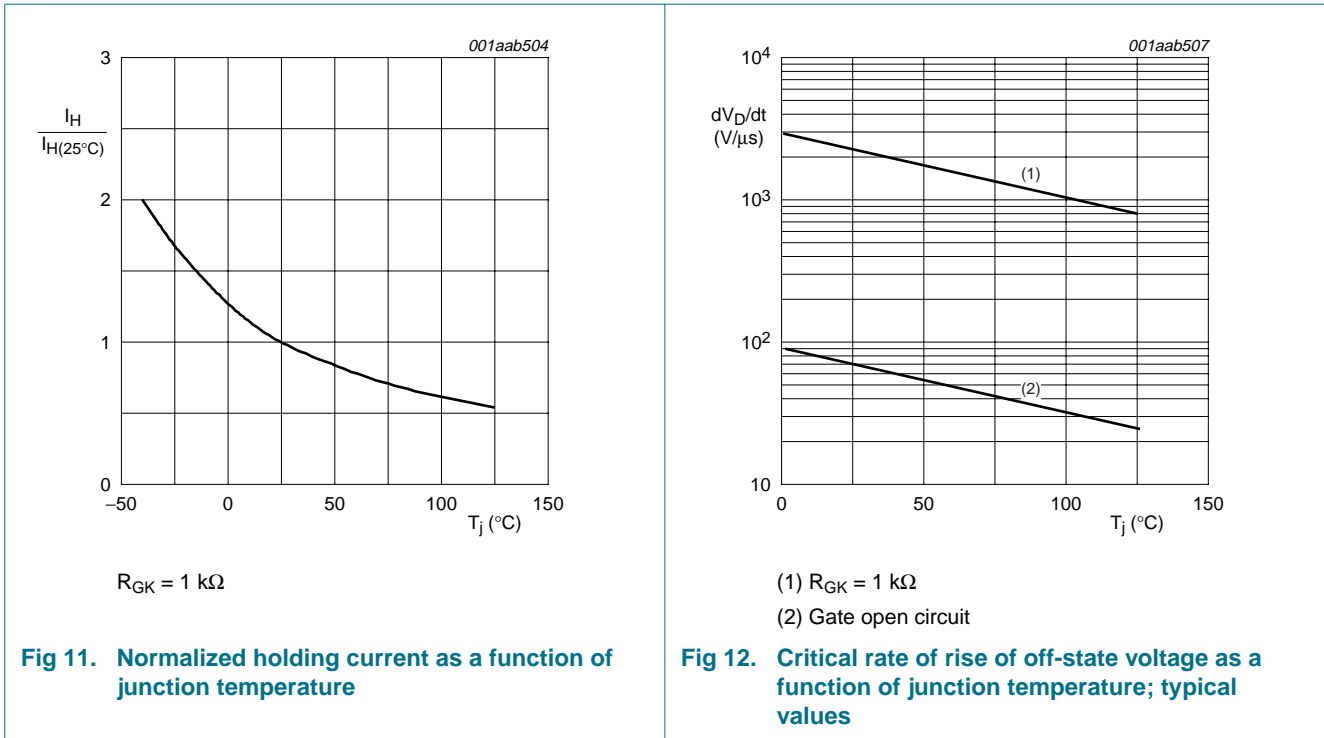
$V_o = 1.067\text{ V}$   
 $R_s = 0.187\ \Omega$   
 (1)  $T_j = 125\text{ }^\circ\text{C}$ ; typical values  
 (2)  $T_j = 125\text{ }^\circ\text{C}$ ; maximum values  
 (3)  $T_j = 25\text{ }^\circ\text{C}$ ; maximum values

Fig 9. On-state current as a function of on-state voltage



$R_{GK} = 1\text{ k}\Omega$

Fig 10. Normalized latching current as a function of junction temperature



## 7. Package information

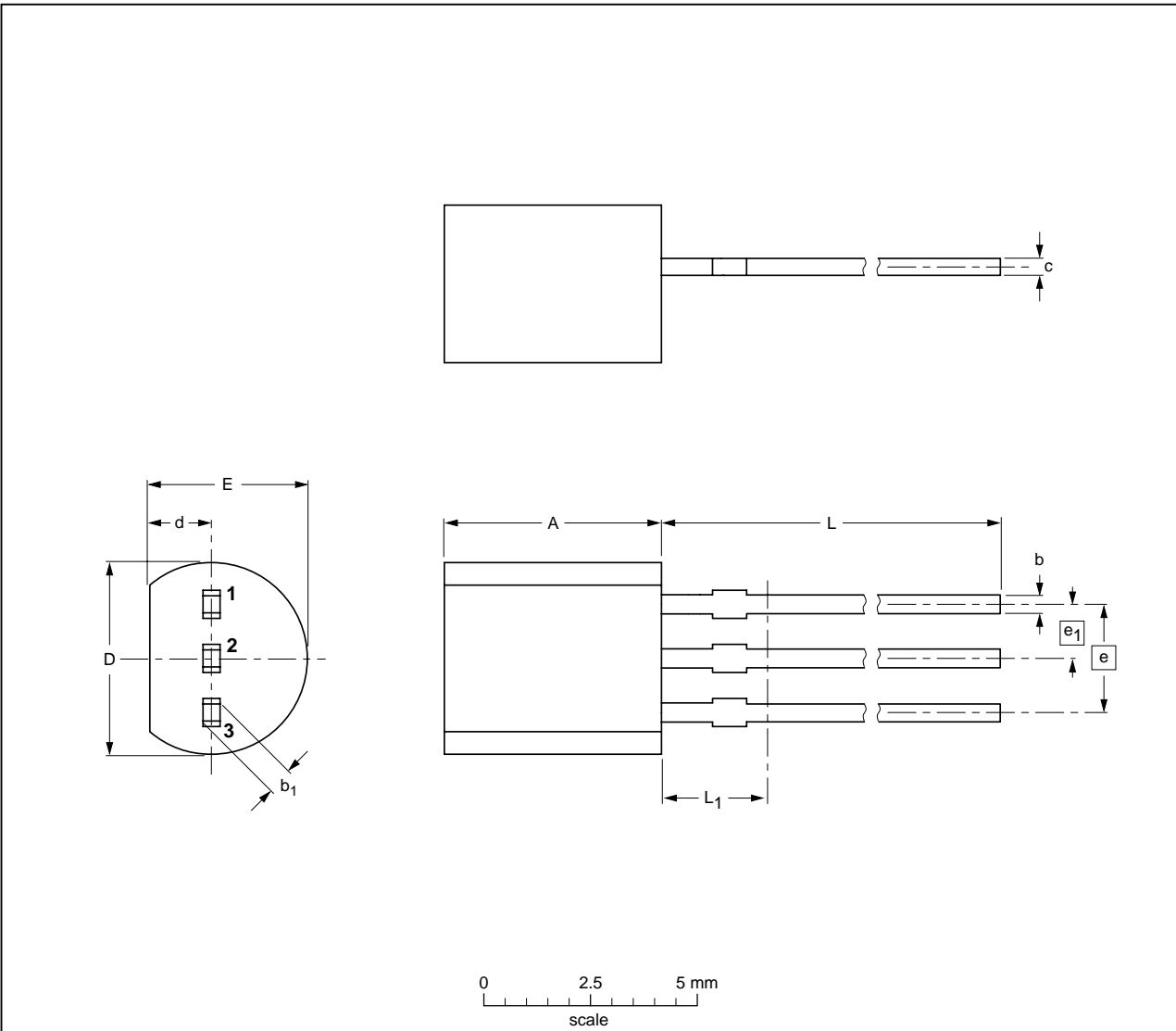
Epoxy meets requirements of UL 94 V-0 at 3.175 mm.



8. Package outline

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b <sub>1</sub>	c	D	d	E	e	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.
mm	5.2	0.48	0.66	0.45	4.8	1.7	4.2	2.54	1.27	14.5	2.5
	5.0	0.40	0.55	0.38	4.4	1.4	3.6				

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT54		TO-92	SC-43A		04-06-28 04-11-16

Fig 13. Package outline SOT54 (TO-92)

## 9. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BT169D-L_2	20080226	Product data sheet	-	BT169D-L_1
Modifications:				
				<ul style="list-style-type: none"><li>• <a href="#">Section 1.2 "Features" on page 1</a>: updated.</li><li>• <a href="#">Section 1.4 "Quick reference data" on page 1</a>: condition <math>I_{TSM}</math> updated.</li><li>• <a href="#">Table 3 "Limiting values" on page 2</a>: table note 1 removed.</li><li>• <a href="#">Table 5 "Characteristics" on page 6</a>: conditions <math>I_{GT}</math>, <math>I_L</math>, <math>I_H</math> and <math>V_{GT}</math> updated.</li></ul>
BT169D-L_1	20071112	Product data sheet	-	-

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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## 12. Contents

<b>1</b>	<b>Product profile</b> . . . . .	<b>1</b>
1.1	General description . . . . .	1
1.2	Features . . . . .	1
1.3	Applications . . . . .	1
1.4	Quick reference data . . . . .	1
<b>2</b>	<b>Pinning information</b> . . . . .	<b>1</b>
<b>3</b>	<b>Ordering information</b> . . . . .	<b>2</b>
<b>4</b>	<b>Limiting values</b> . . . . .	<b>2</b>
<b>5</b>	<b>Thermal characteristics</b> . . . . .	<b>5</b>
<b>6</b>	<b>Characteristics</b> . . . . .	<b>6</b>
<b>7</b>	<b>Package information</b> . . . . .	<b>8</b>
<b>8</b>	<b>Package outline</b> . . . . .	<b>9</b>
<b>9</b>	<b>Revision history</b> . . . . .	<b>10</b>
<b>10</b>	<b>Legal information</b> . . . . .	<b>11</b>
10.1	Data sheet status . . . . .	11
10.2	Definitions . . . . .	11
10.3	Disclaimers . . . . .	11
10.4	Trademarks . . . . .	11
<b>11</b>	<b>Contact information</b> . . . . .	<b>11</b>
<b>12</b>	<b>Contents</b> . . . . .	<b>12</b>

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